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Serial No. 10/634,440

PATENT

*Amendments to the Specification*

At page 1 of the specification, please make the following changes to paragraph [0001]:

This application is a divisional application of Serial No. 10/052,823 filed January 17, 2002, now United States Patent No. 6,649,018. All applications are hereby incorporated by reference in their entireties.

Replace the Examiner's Amendment Abstract with the following Abstract:

A method of removing photoresist from semiconductor wafers through the use of a sparger plate. According to the inventive method, at least one semiconductor wafer is positioned in a process tank above the sparger plate. A mixture of ozone and deionized water is introduced into the process tank at a position below the sparger plate. The mixture of ozone and deionized water is then introduced across the wafer via the sparger plate at an increased flow velocity while the wafer is submerged in the mixture of deionized water and ozone.